BROADCOM

PCN-STB-001852

Product Change Notice

Issue Date: March 02, 2020

Change Type:
Add Assembly Production Site – ASE Taiwan

Parts Affected:
45308KFSB1-C0T
45308KFSB2-C0T
45308KFSB3-C0T
45308XKFSB1-C0T
45308XKFSB2-C0T
45308XKFSB3-C0T
45308XPKFSBC0T

Description and Extent of Change:
Add ASE Taiwan as the assembly supplier for the above device

Reasons for Change:
Supply Chain manufacturing flexibility and capacity

Effect of Change on Fit, Form, Function, Quality, or Reliability:
There will be no change in fit, form, function, quality or reliability

Effective Date of Change:
June 01, 2020

Software / Firmware Update:
There will be no changes in Software / Firmware

Qualification Data:

Package Qualification Reference#:	004487
Fab Technology:	28nm
Package Type:	FCBGA+HS
Package Size:	35 x 35
Lead Count:	1413

Stress Test	Condition	Read points Cycles / Hrs.	Sample Size	Requirements	Results (# fail/ss)
Precondition	MSL3 JESD22-A113E		154 units	0 failures	0 / 154
Temp Cycle	-55°C / 125°C JEDEC Std. 22-A104-C Cond. B	1000 cycles	77 units	0 failures	0 / 77
uHast	130°C/85%RH JEDEC Std. 22-A102-C	96hrs	77 units	0 failures	0 / 77
HTSL	TA=150°C	1000hrs	77 units	0 failures	0 / 77

Please contact your Broadcom field sales engineer or Contact Center for any questions or support requirements. Please return any response as soon as possible, but not to exceed 30 days.